

TITLE: ETCHANT FORMULATION FOR SELECTIVELY REMOVING THIN FILMS IN THE PRESENCE OF  
COPPER, TIN, AND LEAD  
INVENTORS NAME: Donald Danielson et al.  
DOCKET NO.: 884.614US1

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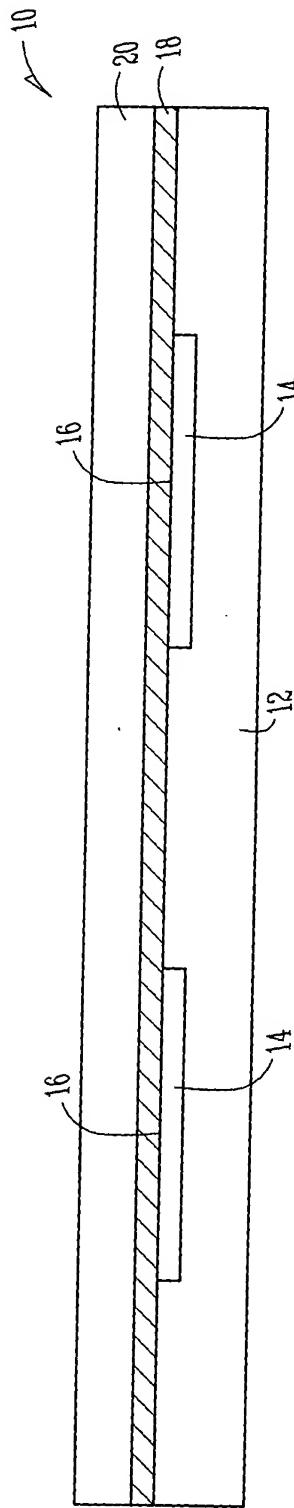


Fig. 1

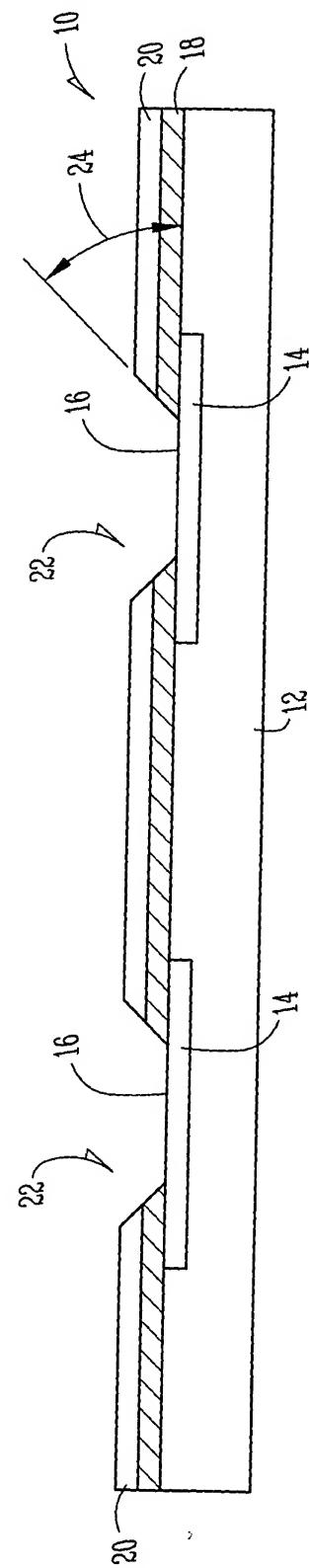


Fig. 2

TITLE: ETCHANT FORMULATION FOR SELECTIVELY REMOVING THIN FILMS I

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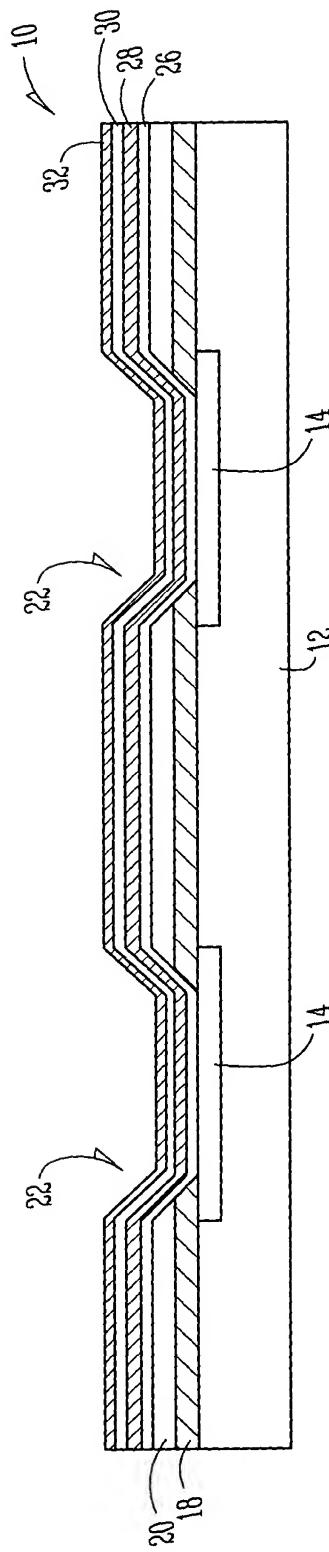


Fig. 3

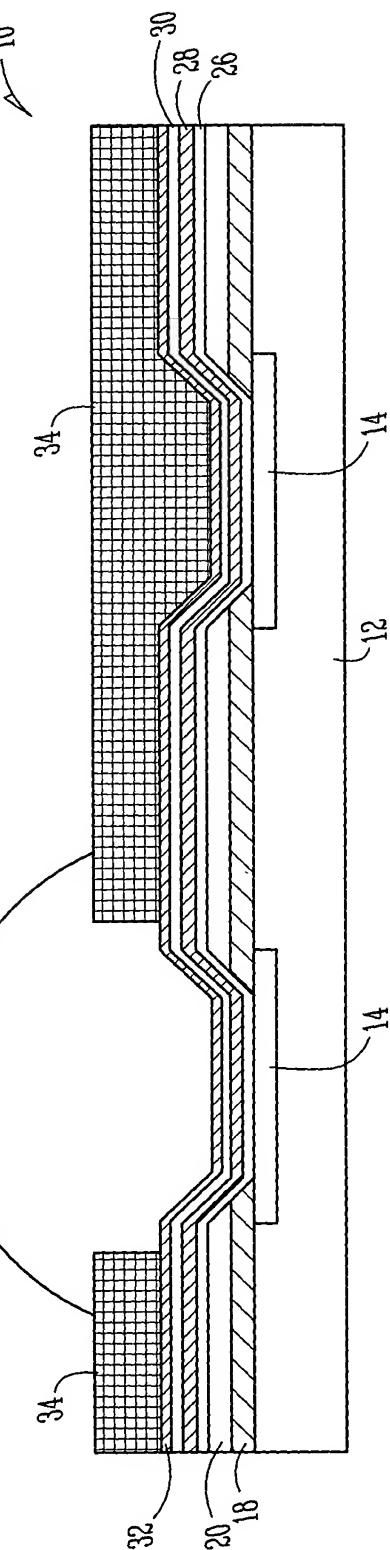


Fig. 4

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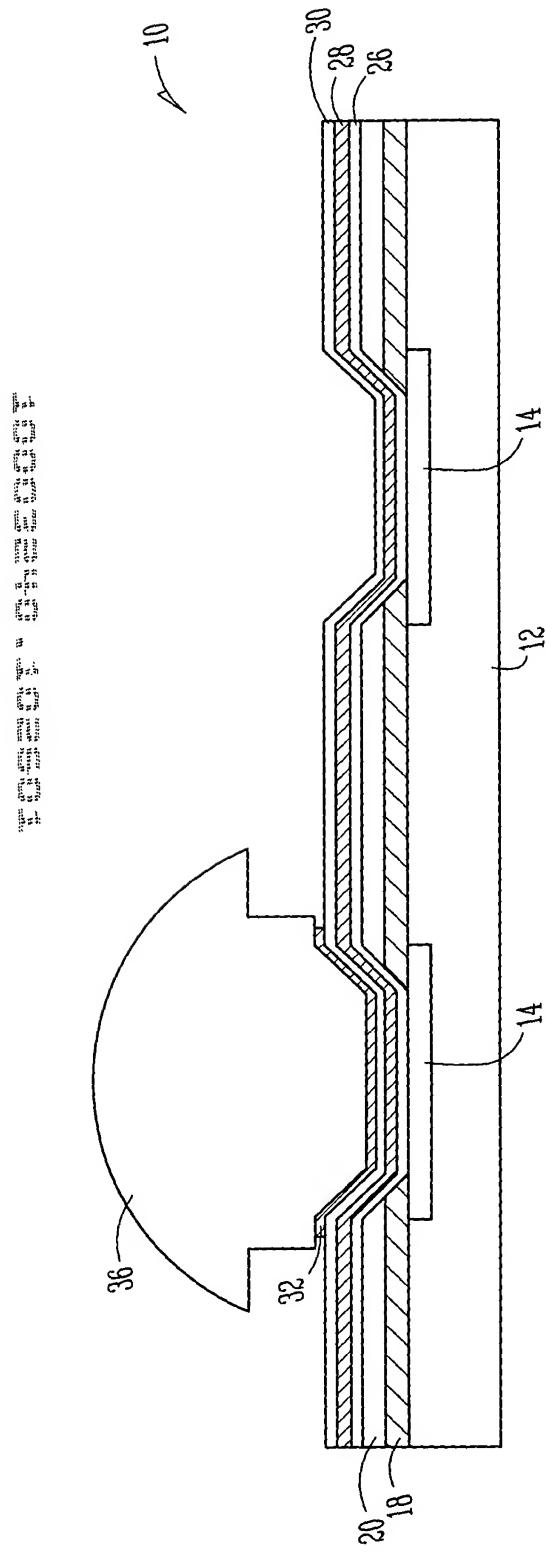


Fig. 5

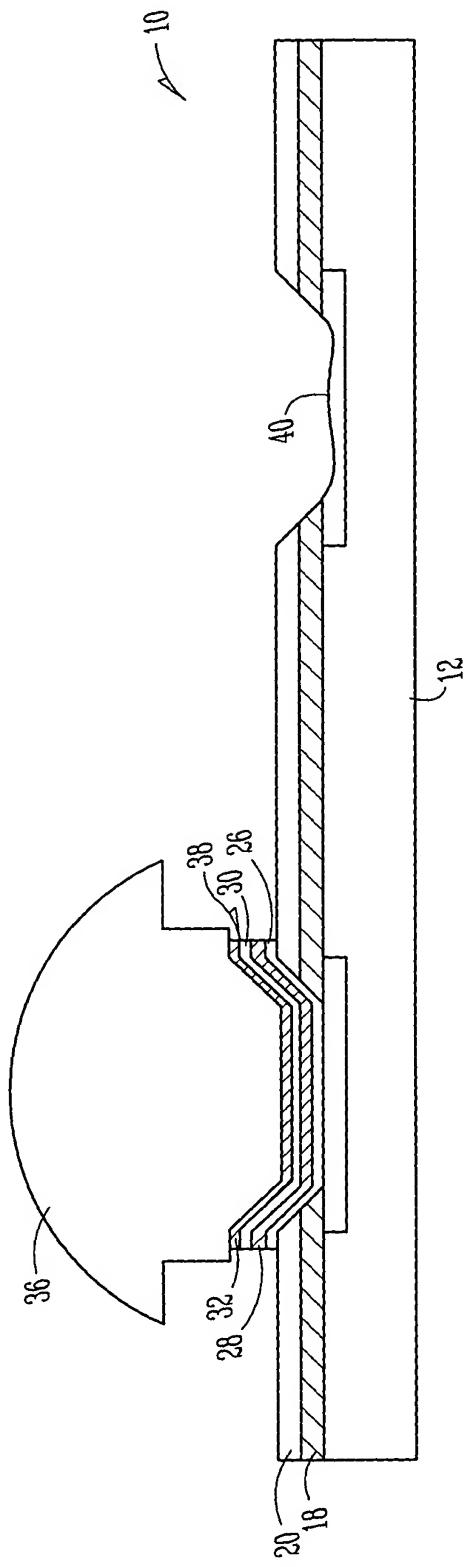


Fig. 6

TITLE: ECHANT

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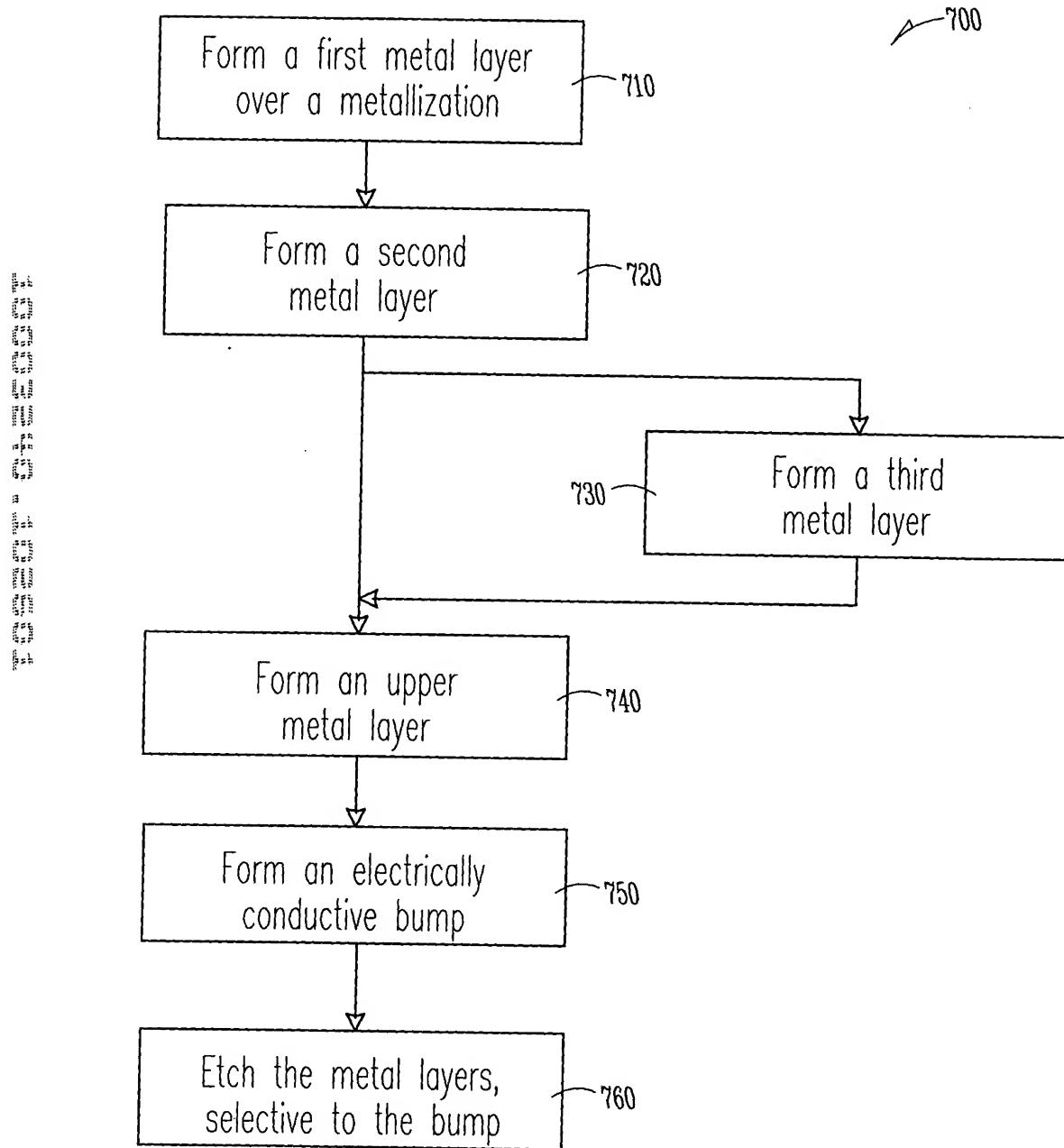


Fig. 7